



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-09-12
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana San Biagio	<b>Representative Title</b>	AMG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FBIO*UP63J51	A	ZY1A	2016-09-12
Amount	UoM	Unit type	ST ECOPACK Grade	
59.40	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5x4.4x1	16	gull wing	
Comment	Package: IO HTSSOP 16 4.4 PITCH 0.65 EXPAD; MDF valid for STP08CP05XTTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	FBI0*UP63J51					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.149	mg	supplier	die	Silicon (Si)	7440-21-3		1.096	mg	953873	18451
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	9574	185
				supplier	metallization	Tungsten (W)	7440-33-7		0.009	mg	7833	152
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	1741	34
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	16536	320
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.012	mg	10444	202
Leadframe	Copper & its alloys	26.005	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.671	mg	948702	415337
				supplier	alloy	Nickel (Ni)	7440-02-0		0.769	mg	29571	12946
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.038	mg	1461	640
				supplier	alloy	Silicon (Si)	7440-21-3		0.167	mg	6422	2811
				supplier	metallization	Silver (Ag)	7440-22-4		0.360	mg	13843	6061
Die attach	Other Organic Materials	0.919	mg	supplier	glue	Silver (Ag)	7440-22-4		0.734	mg	798694	12357
				supplier	glue	Bisphenol F type epoxy resin	9003-36-5		0.073	mg	79434	1229
				supplier	glue	Epoxy resin	68475-94-5		0.028	mg	30468	471
				supplier	glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.028	mg	30468	471
				supplier	glue	Gamma Butyrolactone	96-48-0		0.028	mg	30468	471
				supplier	glue	Polyoxypropylenediamine	9046-10-0		0.028	mg	30468	471
Bonding wires	Precious metals	0.567	mg	supplier	wire	Gold (Au)	7440-57-5		0.567	mg	1000000	9545
Encapsulation	Other Organic Materials	30.170	mg	supplier	mold compound	Silica, vitreous	60676-86-0		26.127	mg	865993	439848
				supplier	mold compound	Epoxy Resin	Proprietary		2.262	mg	74975	38081
				supplier	mold compound	Phenol Resin	Proprietary		1.509	mg	50017	25404
				supplier	mold compound	Carbon black	1333-86-4		0.151	mg	5005	2542
				supplier	mold compound	Bismuth compound	7440-69-9		0.121	mg	4011	2037
connections coating	Solder	0.590	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.590	mg	1000000	9933